



ECCOBOND™ E 6752

Surface Mount Adhesive For Very High Speed Dispensing

Key Feature:	Benefit:
• High dot profile	• Fills board to component gap
• High adhesion	• No lost components
• Low stringing	• No conductive pad contamination
• Long shelf life	• Excellent product stability

Product Description:

ECCOBOND E 6752 is a one component, low temperature curing surface mount adhesive that applies easily without stringing. It will not sag during cure. Low shrinkage during cure and low coefficient of thermal expansion result in minimal stress on bonded components. This single component adhesive cures in 3-5 minutes at 120°C in IR and prevents component movement during board handling or cure.

ECCOBOND E 6752 is the red version of ECCOBOND E 6750

Applications:

ECCOBOND E 6752 is designed specifically for use in high-speed pneumatic and positive displacement dispensers. ECCOBOND E 6752 is an excellent adhesive for bonding a complete range of components, including chip capacitors and resistors, SOTs, SOICs, and PLCCs.

Instructions For Use:

Thoroughly read the information concerning health and safety contained in this bulletin before using. Observe all precautionary statements that appear on the product label and/or contained in individual Material Safety Data Sheets (MSDS).

ECCOBOND E 6752 is applied by syringe dispensing. Equipment set-up parameters and related product information are available worldwide from your Henkel Corporation technical support group.

Properties of Material As Supplied:

Property	Test Method	Unit	Value
Chemical Type			Epoxy
Appearance	Visual		Red, Fluorescent
Fineness	Hegman	µm	<50
Density	TP-13	g/cm ³	1.16
Brookfield Viscosity	TP-10 or TP-11 1 rpm # TD	Pa.s cP	850 850,000
	10 rpm # TD	Pa.s cP	185 185,000
Plastic Viscosity (Casson)	Cone - plate	Pa.s cP	27 27,000
Calculated Yield (Casson)	Cone - plate	N/m ²	2,800

Tps are internal test procedures typically derived from ASTM or other norms. Copies of these procedures can be obtained upon request.

Cure Schedule:

ECCOBOND E 6752 can be cured by infrared or by convection oven. Cure times will depend on cure temperatures. A ramp up temperature of not more than 1°C per second should be used.

Temperature °C	Cure Time (minutes)	
	IR or Convection Conveyor Oven	Convection Box Oven
100	20	30
110	10	20
120	3.5	10

Properties of Material After Application:

Property	Test Method	Unit	Value
Hardness	TP-311	Shore D	>80
Tensile Lap Shear Strength FR 4 to FR 4 @ 25°C	TP-21	mPa psi	13.8 2,000
Glass Transition Temperature	DSC / TMA	°C	65
Thermal Conductivity	ASTM-D-2214	W/m.K Btu-in/hr-ft ² -°F	0.25 1.73
Temperature Range of Use		°C	-40 to +105
Dielectric Constant	TP-184	-	3.5
Volume Resistivity @ 25°C	TP-183	Ohm-cm	10 ¹⁴
Electromigration	Bellcore		Passed

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Storage and Handling:

The shelf life of ECCOBOND E 6752 is 6 months at 0°C or 3 months at 25°C. For best results, store in original, tightly covered containers. Store in a cool, clean and dry area. When ECCOBOND E-6752 is stored at low temperatures, it must be allowed to return to room temperature before use. This normally takes 2 hours.

Health and Safety:

The ECCOBOND E 6752, like many industrial compounds, possesses the ability to cause severe skin and eye irritation upon contact. Certain individuals may also develop an allergic reaction after exposure (skin contact, skin absorption, inhalation of vapors, etc.) which may manifest itself in a number of ways including skin rashes, itching sensations and breathing difficulties. Components of this product may be absorbed through the skin. Handling this product at elevated temperatures may also generate vapors irritating to the respiratory system.

Good industrial hygiene and safety practices must be followed when handling this product. Proper eye protection and appropriate chemical resistant clothing should be worn to minimize direct contact and prevent possible skin absorption. Consult the Material Safety Data Sheet (MSDS) for detailed recommendations on the use of engineering controls and personal protective equipment.

This information is only a brief summary of the available safety and health data. Thoroughly review the MSDS for more complete information before using this product.

Attention Specification Writers:

The values contained herein are considered typical properties only and are not intended to be used as specification limits. For assistance in preparing specifications, please contact Henkel Corporation Quality Assurance for further details.

Medical Implantable Disclaimer

"In the event this product is intended by you for use in implantation in the human body, you are hereby advised that Henkel Corporation has not performed clinical testing of these materials for implantation in the human body nor has Henkel Corporation sought, nor received, approval from the FDA for the use of these material in implantation in the human body. It is YOUR responsibility, as a manufacturer of any such device, to ensure that all materials and processes relating to the manufacture of any medical device fully comply with all applicable federal, state and local laws, rules, regulations and requirements as well as any such laws, rules, regulations, directives or other orders of any foreign country where such product is sold. If you have not undertaken the necessary investigations to ensure compliance you are advised NOT TO USE this product in the manufacture of any device which is to be implanted in the human body. No representative of ours has any authority to change the foregoing provisions."

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